

ABSTRACT

1 A method for depositing a solder layer or solder bump on a sloped surface. The
2 method includes etching a sloped surface on a planar semiconductor substrate, depositing
3 a solder-wettable layer on the sloped surface, masking the wettable layer with a coating
4 layer to control the position of the solder deposition, and using an organic film to prevent
5 the solder from being deposited at regions not above either the wettable layer or the
6 coating layer. Also, a semiconductor device structure on which a solder layer or solder
7 bump is formed exclusively on a sloped surface.